

PRODUCT CHANGE NOTIFICATION (PCN)

(According to JEDEC standard JESD046)

PCN number: GC244787

Date: 05-December-2024

Title: FPBGA Encapsulation site change, Moisture Sensitivity Level downgrading & laser marking for data converters EV10DS130xx, EV12DS130 and EV12DS400/460/480xx series

Product identification:

EV10DS130ACZPY	EV12DS400ACZPY	EVX12DS480AZPY
EV10DS130AVZPY	EV12DS400AVZPY	EV12DS480ACZPY
EV10DS130BCZPY	EV12DS400AMZPY	EV12DS480AVZPY
EV10DS130BVZPY	EV12DS400ACZP	EV12DS480AMZPY
	EV12DS400AVZP	EV12DS480ACZP
	EV12DS400AMZP	EV12DS480AVZP
EV12DS130ACZPY		EV12DS480AMZP
EV12DS130AVZPY		EV12DS480AMZP-E3
EV12DS130AVZP	EV12DS460ACZPY	EV12DS480AMZP-EP
EV12DS130AMZP-E3	EV12DS460AZZPYW1	EV12DS480AMZP-N1
EV12DS130AMZP-EP	EV12DS460AVZPY	EV12DS480AMZP-E1
EV12DS130AMZP-N1	EV12DS460AMZPY	
EV12DS130BCZPY	EV12DS460ACZP	
EV12DS130BVZPY	EV12DS460AVZP	
EV12DS130BVZP	EV12DS460AMZP	
EV12DS130BMZP-E3		
EV12DS130BMZP-EP		
EV12DS130BMZP-N1		

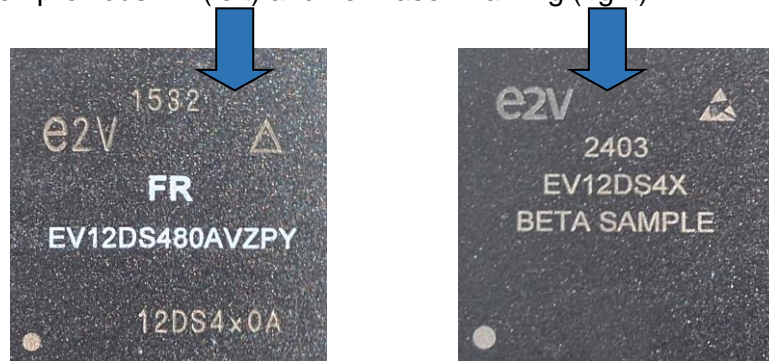
Reason for change:

- | | | | |
|------------------------------------|--|--|---------------------------------|
| <input type="checkbox"/> Design | <input checked="" type="checkbox"/> Material | <input checked="" type="checkbox"/> Processing | <input type="checkbox"/> Other: |
| <input type="checkbox"/> Logistics | <input checked="" type="checkbox"/> Manufacturing Location | <input type="checkbox"/> Quality/Reliability | |

Change(s) description:

- Change of FPBGA196 assembly subcontractor. Assembly will be performed at Teledyne-e2v premise.
- Molding reference material will change.
 - Thermal characteristics will remain the same as the datasheet stated.
 - The Moisture Sensitivity Level (MSL) will be downgraded from MSL3 to MSL4 according to J-STD-020. The labelling and the datasheet will be changed accordingly.
- Change of laser marking instead of ink marking. This aligns with the supplier direction and industry environmental initiatives. It will also further improve the marking permanency. P/N reference and marking information content remain the same.

See below evolution between previous ink (left) and new laser marking (right):



Identification method to distinguish change:

All Date Code equal or greater than DC 2501 will reflect the new assembly location.
 P/N reference and marking information content remain the same.
 The labelling of the dry pack will show now MSL4 instead of MSL3

Note: Present PCN supersede previously posted GC222043 from 24 May 2022

Qualification data: Already available Will be available in March-2025 Not applicable

Qualification samples: Already available Will be available in Not applicable

Quantifiable impact & reliability:

Except the form evolution due to the marking nature, no other changes will be brought in form, fit, or function.

Downgrading the MSL rating from MSL3 to MSL4 did not change the defined peak reflow temperature of the product.

No impact on reliability.

Implementation date: Estimated March-2025

The Estimated Implementation Date is the forecasted date that a customer may expect to receive changed product. This is determined by the estimated date of inventory depletion on the PCN issue date. This may be affected by fluctuations in supply and demand. Consequently, although customers should be prepared to receive changed product on this date, Teledyne will continue to ship pre-changed product until a time in which inventory has been depleted. This may result in pre-changed product being shipped to customers after this forecasted date.

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Approved by:

Quality / Product Manager

Marketing / Quality Director

Name S.Renaud

Name N.Boeuf

Teledyne will deem this change accepted unless specific conditions of acceptance are provided in writing within 30 days from the date of this notice. All correspondence must be sent to the contact e-mail addresses indicated above.

Teledyne assumes no responsibility for any errors that may appear in this document.

The supply of products will be subject to Teledyne general terms and conditions of sale, or any specific contractual terms agreed between the parties.

Please consult our other announcements (PCN, EOL) on our web page:

<https://semiconductors.teledyneimaging.com/en/products/lifecycle-management-obsolence/>